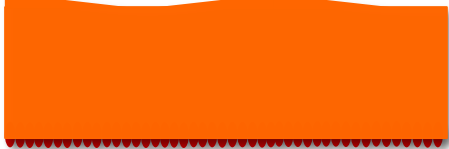


HS1-VSP® / HS2-VSP® / SI-VSP® / SI2-VSP® / SI3-VSP® / SF-VSP®

高速訊號傳輸用電解銅箔

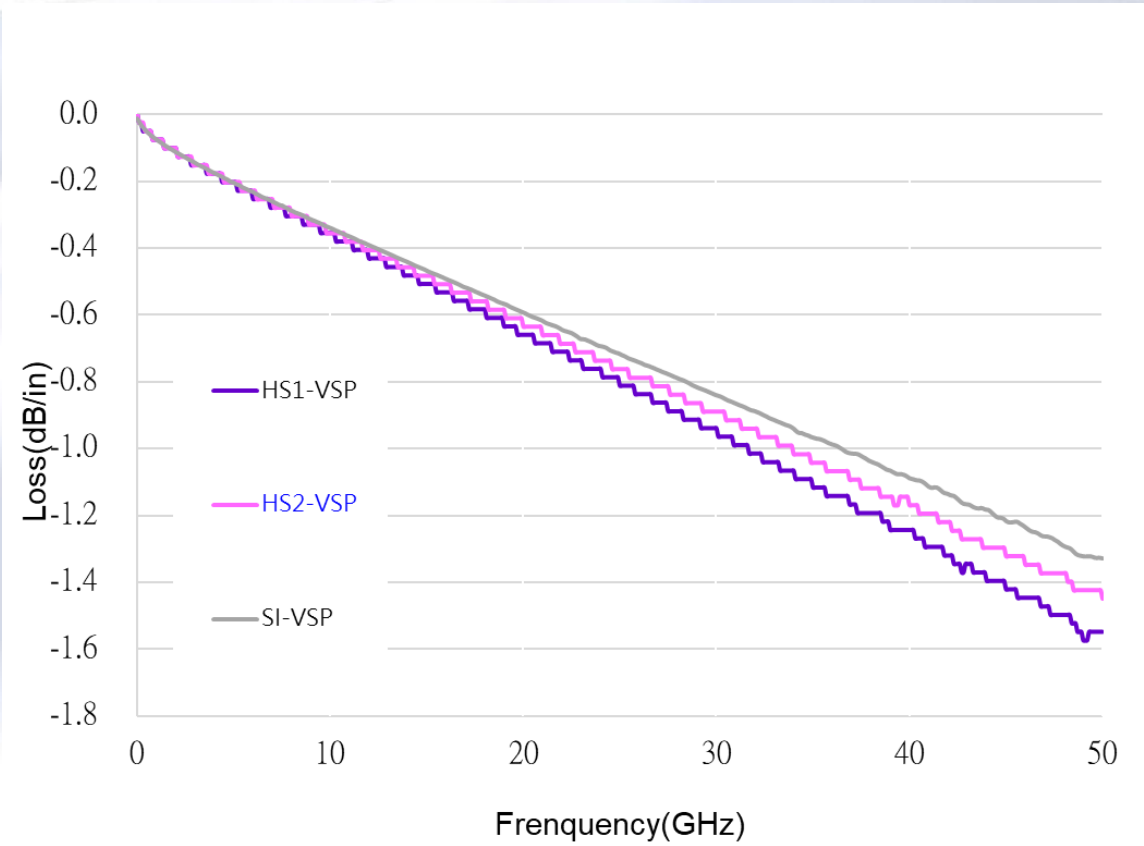
ED copper foil series for high speed data transmission

- VSP®系列低粗糙度銅箔, 應用於Low Dk/Df板材, 更具低訊號損失特性.
- VSP® copper foils with very low profile.
- Combined with low Dk/Df materials to show very low signal loss.
- 表面處理技術於 Low Dk/Df 膠系具優良的黏合特性.
- Good bonding characteristics with low Dk/Df materials.

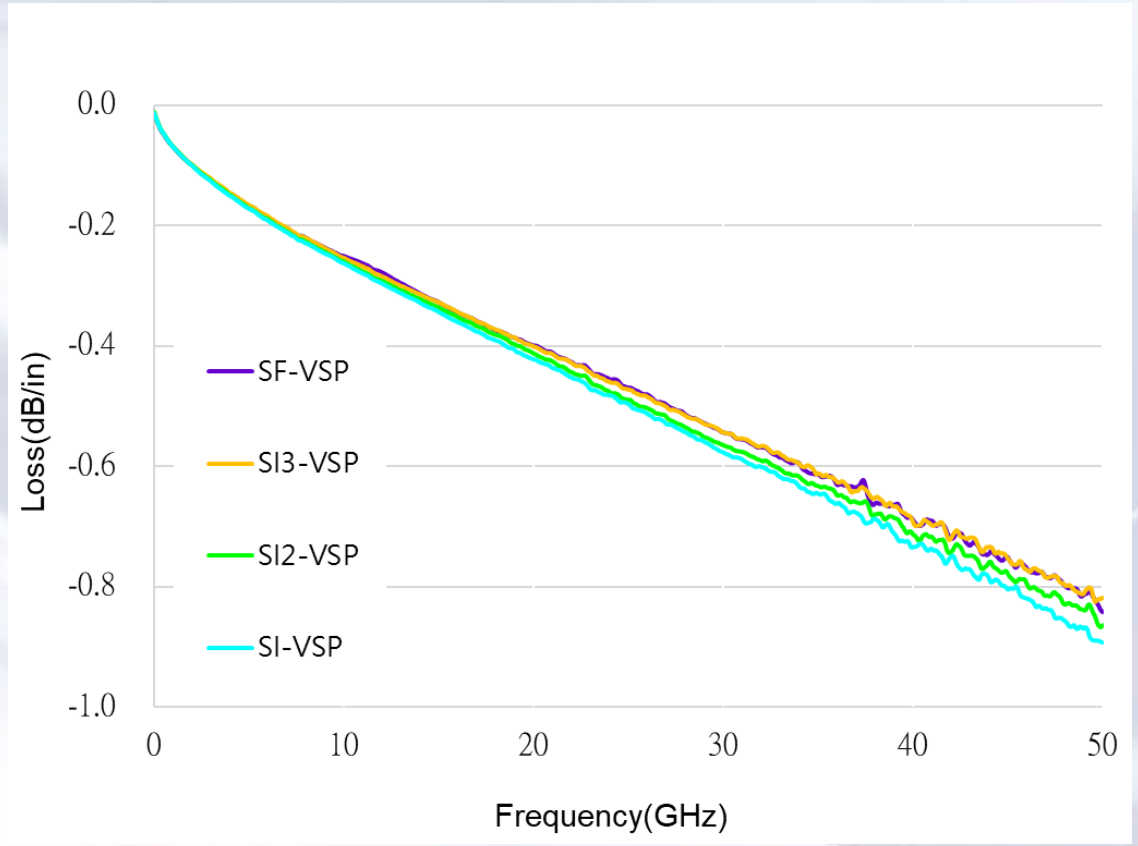
Product	Cross Section Image	Roughness B-side Rz	Thickness	Status
MLS®-G3 MLS®-G4		1.5um	Toz/Hoz/1oz/2oz	Mass Production
 HS1-VSP® HS2-VSP®		1.5um 1.0um		
 SI-VSP® SI2-VSP®		0.6um 0.5um		
 SI3-VSP® (Draft) SF-VSP® (Draft)		0.4um	Toz/Hoz/1oz	Sampling

■ 高頻訊號損失比較 Signal Loss at high frequency (SI data)

Dielectric: Low loss Prepreg 136um, Dk 3.4 Df 0.004
 Cu thickness : 18um Impedance : 50 Ω
 Measurement mode : Microstrip Line / Single



Dielectric: Low loss Prepreg 136um, Dk 3.22 Df 0.0014
 Cu thickness : 18um Impedance : 50 Ω
 Measurement mode : Microstrip Line / Single



*上述表列為代表性資料,非保證值。 * This is representative data not guarantee